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*******DRAFT - DO NOT FILE*******

The paragraph beginning at page 9, line 17 is amended as follows:

It is noted in Figures 1-4 that one occurrence of metallization 14 has no bump precursor button 36 due to the patterning of mask 34 that has prevented deposition of solder material. In such an event, the metallization without a bump precursor button may act as a probe site for testing or other functions.

IN THE CLAIMS

Please amend the claims as follows:

20. (Amended) The BLM etching system according to claim 15, wherein the [refractory] metal upper layer is selected from a metal, refractory metal, metal-doped refractory metal, or a refractory metal alloy selected from Ni, Co, Pd, Pt, NiV, CoV, PdV, PtV, Ti, Zr, Hf, Cr, Mo, W, Sc, Y, La, and Ce in a solid-solution or stoichiometric ratio.